



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 360F H6327		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000895772						
<b>Package</b>		PG-TSFP-3-1		<b>Weight*</b>		1.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.03		324	
	noble metal	gold	7440-57-5	0.002	0.13		1258	
	inorganic material	silicon	7440-21-3	0.013	0.93	1.09	9323	10905
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		80	
	non noble metal	titanium	7440-32-6	0.001	0.04		400	
	non noble metal	chromium	7440-47-3	0.002	0.12		1199	
	non noble metal	copper	7440-50-8	0.570	39.79	39.96	397855	399534
wire	noble metal	gold	7440-57-5	0.004	0.28	0.28	2751	2751
encapsulation	organic material	carbon black	1333-86-4	0.008	0.55		5458	
	plastics	epoxy resin	-	0.168	11.73		117345	
	inorganic material	silicondioxide	60676-86-0	0.607	42.29	54.57	422989	545792
leadfinish	non noble metal	tin	7440-31-5	0.034	2.36	2.36	23644	23644
plating	noble metal	silver	7440-22-4	0.025	1.74	1.74	17374	17374
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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